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♥Title:

JP2000061683A2: SOLDER PLATED WIRE

JP Japan

₩Kind:

A2 Document Laid open to Public inspection 1

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**₽**Abstract:

PROBLEM TO BE SOLVED: To obtain a solder excellent in solder wettability, excellent in heat resisting strength hardly generating thermal creep under a high temperature environment and containing no harmful Pb by providing a plating layer comprising Bi, Ag, Cu, and the balance Sn with inevitable impurities with a specified weight-based ratio on the outer peripheral surface of a metallic element wire.

SOLUTION: The plating layer comprises, by weight, 1.0-30% Bi, 0.5-10% Ag, 0.01-2% Cu, and the balance Sn with inevitable impurities. This solder plated wire is improved in solder wettability, so solder connecting workability is improved and man-hour of working for electronic instrument or the like is reduced. Heat resisting strength of soldered part is improved, thermal creep even under a high temperature atmosphere is hardly generated no dropping-off of solder plated wire out of soldered part happens, and reliability of solder connecting part is improved. Further, the surface of the plating is hard and hardly flawed, ill appearance of the solder plated wire is decreased, and no harmful Pb component is contained, so that safety with respect to health and environment is

secured.

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₽ Family:

None

**ਊOther Abstract** 

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